

Abstract of the Disclosure

A circuit board 10 including first components 30 which are mounted by solder connection, and a second component 36 which is mounted with an ACF 40 interposed therebetween. The circuit board 10 has a band-shaped region A3 which extends in the shape of a band and includes the second component 36, but none of the first components 30. The band-shaped region A3 is wider than the pressing surface of a thermocompression bonding head which is employed in mounting the second component 36.